

# HZM6.8MFA

## Silicon Planar Zener Diode for Surge Absorb

REJ03G1209-0200

(Previous: ADE-208-833A)

Rev.2.00 Jun 13, 2005

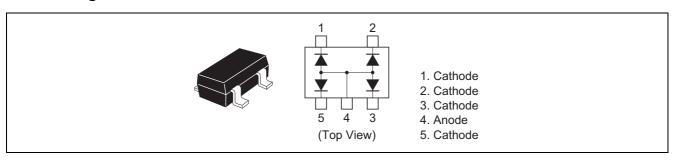
### **Features**

- HZM6.8MFA has four devices in a monolithic, and can absorb surge.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

## **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZM6.8MFA	68M	MPAK-5	PLSP0005ZC-A
			(MPAK-5)

### **Pin Arrangement**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	−55 to +150	°C

Note: Four device total, See Fig.2.

## Electrical Characteristics \*1

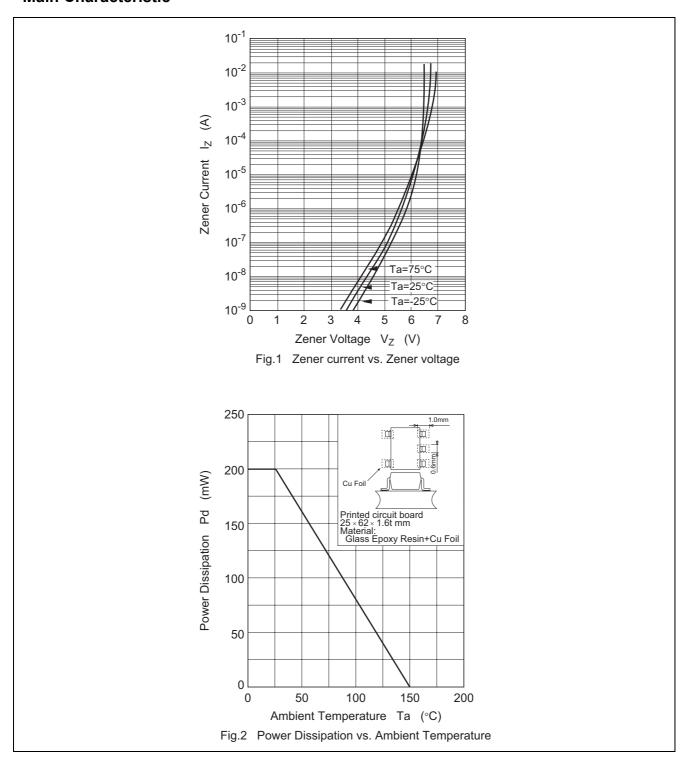
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	6.47	_	7.00	V	$I_Z$ = 5 mA, 40 ms pulse
Reverse current	I <sub>R</sub>	_	_	2	μΑ	V <sub>R</sub> = 3.5 V
Capacitance	С	_	_	130	pF	V <sub>R</sub> = 0 V, f = 1 MHz
Dynamic resistance	r <sub>d</sub>	_	_	30	Ω	$I_Z = 5 \text{ mA}$
ESD-Capability *2	_	30	_	_	kV	C = 150 pF, R = 330 $\Omega$ , Both forward and reverse direction 10 pulse.

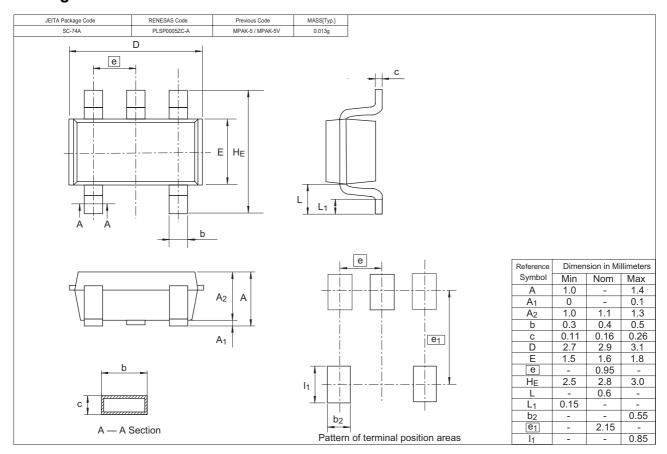
Notes: 1. Per one device

2. Failure criterion ;  $I_R > 2 \mu A$  at  $V_R = 3.5 V$ .

### **Main Characteristic**



## **Package Dimensions**



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